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### REMARKS

Favorable reconsideration of this application is respectfully requested in view of above amendments and following remarks.

The specification is amended to correct typographical errors. Particularly, the listed oxides have been respectively revised from  $\text{Bi}_2\text{O}_2$  and  $\text{Al}(\text{NO}_3)_2$  to  $\text{Bi}_2\text{O}_3$  and  $\text{Al}(\text{NO}_3)_3$ . Applicants respectfully submit that this is a readily apparent error. Claims 8 and 25 are also amended to correct this error.

Claims 1 and 20 are amended, as supported for example at page 5, lines 18-20 of Applicants' disclosure. Claims 4, 23, 26, and 27 are editorially revised. Claim 28 is added and supported for example in original claim 6 (now canceled). No new matter has been added. Claims 1-5, 8, 10, 12, 13, and 20-28 are pending.

Claims 26 and 27 are objected to for informalities. Claims 26 and 27 have been corrected to address the misspellings noted in the Office Action. Applicants respectfully submit that the claims are in proper form.

Withdrawal of the rejection is respectfully requested.

Claims 1-3, 5, 8, 12, 20-22, 24, and 25 are rejected under 35 U.S.C. 103(a) as being unpatentable over Fukuoka (JP 57-067191). Applicants respectfully traverse this rejection.

Claims 1 and 20 are directed to an aqueous solution for forming a copper-to-resin bonding layer. The solution includes a reaction accelerator that coordinates to copper as a base material to form a chelate and facilitates forming a bonding layer for bonding resin on a copper surface.

However, Fukuoka does not teach or suggest the features of claims 1 and 20. Fukuoka does not teach or suggest an aqueous solution having a reaction accelerator that coordinates to copper as a base material to form a chelate and facilitates forming a bonding layer for bonding resin on a copper surface. In fact, the reference aims to form a Sn-Co alloy plated film and discloses a composition containing electrically conductive salts such as KCl, NaCl, and the like. However, the disclosed materials of Fukuoka do not satisfy claims 1 and 20, and such materials do not have the properties required for the reaction accelerator of claims 1 and 20. For at least the foregoing, claims 1 and 20 and the remaining claims dependent therefrom are patentable.

Favorable reconsideration and withdrawal of the rejection are respectfully requested.

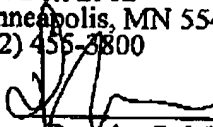
In view of the above amendments and remarks, Applicants believe that the pending claims are in a condition for allowance. A Notice of Allowance is respectfully solicited. If any questions arise regarding this communication, the Examiner is invited to contact the undersigned attorney listed below.



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Respectfully submitted,

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